DESCRIPTION and APPLICATIONS

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

VOLTAGE RANGE
20 to 200 Volts
CURRENT
3.0 Ampere

FEATURES

* Ideal for printed circuit board
* Reliable low cost construction utilizing molded plastic technique
* High surge current capability

MECHANICAL DATA

* Polarity: Symbol molded on body
* Mounting position: Any

Internal Schematic

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MB32F	MB34F	MB36F	MB38F	MB310F	MB315F	MB320F	UNIT
Maximum Recurrent Peak Reverse Voltage	20	40	60	80	100	150	200	V
Maximum RMS Voltage	14	28	42	56	70	105	140	V
Maximum DC Blocking Voltage	20	40	60	80	100	150	200	V
Maximum Average Forward Rectified Current	3.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	8 0							A
Maximum Forward Voltage Drop per Bridge Element at 3.0A D.C.	0.55		0.7	0.85		0.9		V
Maximum DC Reverse Current Ta=25℃	0.3			0.2		0.1		mA
at Rated DC Blocking Voltage Ta=125℃	10			5		2		mA
Typical Thermal Resistance R JA (Note 1)	75							℃/W
Operating Temperature Range, T_J	-55 —+150							℃
Storage Temperature Range, T_{STG}	-55 —+150							℃

NOTE 1: Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

FIG.2-TYPICAL FORWARD CHARACTERISTICS

FIG.3 - TYPICAL REVERSE CHARACTERISTICS

FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

FIG.5-TYPICAL JUNCTION CAPACITANCE

FIG.6 TYPICAL TRANSIENT THERMAL IMPEDANCE

Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition

Package Dimensions & Suggested Pad Layout

MBF

Dimensions	Value (in mm)
C	2.50
X	1.10
X1	3.60
Y	2.10
Y1	7.50

Tape & rell specification

Tape

Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.60±0.15
D1	1.60±0.15
E	1.75±0.20
F	5.50±0.15
W	12.00±0.20
A0	5.30±0.20
B0	7.15±0.20
K0	1.65±0.15
T	0.23±0.10

13” Reel

D2	330.0±5.0
D3	73Min.
D4	16.0±2.5
W1	18.0±3.0
Quantity: 5000PCS	